the first surface of the film of the chip-on-film faces the array substrate, and the connection region is disposed at a side of the array substrate away from a light-emitting surface,

wherein the chip of the chip-on-film is disposed on a side of the chip-on-film closest to the array substrate, and the chip-on-film extends from the one end in an inward direction,

wherein the entirety of the chip-on-film is disposed within an area defined by the outermost edges of the array substrate such that the entirety of the chip-on-film overlaps a non-light emitting surface of the array substrate that opposes the light-emitting surface, and

wherein the printed circuit board is disposed on a side of the array substrate away from the light-emitting surface,

wherein wires on a surface of the printed circuit board are used to transfer signals between electronic components of the printed circuit board, and the surface of the printed circuit board on which the wires are formed faces the array substrate, and

wherein the chip-on-film is directly attached to an upper surface of the printed circuit board that faces away from the array substrate, and the electronic components of the printed circuit board are disposed on the upper surface of the printed circuit board that faces away from the array substrate,

wherein the first surface of the film of the chip-on-film is attached to the upper surface of the printed circuit board that faces away from the array substrate.

2. The display panel according to claim **1**, wherein the display panel is an active matrix organic light emitting diode (AMOLED) display panel.

3. The display panel according to claim **2**, wherein the display panel is an AMOLED display panel which emits light from its bottom.

4. A display apparatus, comprising the display panel according to claim **1**.

5. The display panel according to claim **1**, wherein the entirety of the first surface faces the array substrate.

* * * * *